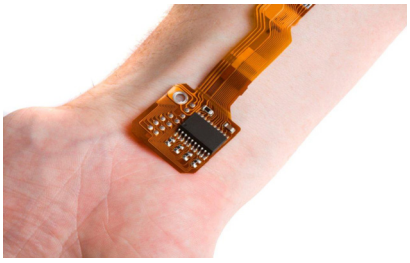
flex-rigid line card

When designing printed circuits, comparing a rigid board to a flex board is akin to placing an apple next to an orange. They're both considered fruits and both grow on trees, yet their tastes are very different. Likewise, flex & rigid boards are both printed circuit boards designed with many of the same specifications, yet their performances are quite different. From simple to complex multilayer flex circuits, we can meet your engineering demands. Please review our capabilities by selecting the Flex Line Card button below.

Standard Features	Standard	Advanced
Inner-layer Trace / Space (0.5 oz)	.004/.004	.003/.003
Outer-layer Trace / Space (1 oz)	.005/.005	.004/.004
Pad Over Drill Size for Tangency (drill + x)	.08	.005
Antipad (Clearance) Over Drill Size	.020	.016
Minimum Mechanical Drill Size	.008	.006
Adhesivless Materials- Copper Thickness	.5oz	2oz
Minimum Core Thickness-Polyimide	.002	.001
Maximum Copper Weight	5 "	10"
Maximum Aspect Ratio	8:1	12:1
Maximum Layer Count	2	8
Maximum Board Thickness	N/A	N/A
Minimum Board Thickness	.021	.008



Rigidizers/Stiffners		
FR4 drilles, routed & scored	Y	Y
Aluminum	Y	Y
Polyimide	Y	Y
Polyester	Y	Y
Stainless Steel	Y	Y

Soldermask Overlay		
Polyimide	.5"	5"
Polyester	1.5"	.3"
Photo-imageable overcoat	Liquid for surface mount & dense applications	

Materials		
FR-4 (min 170Tg (DSC)) Standard	Y	Y
Polymide	Y	Y

Materials (cont.)		
Getek/Megtron (PPO)	Y	Y
Isola (all except 640 Series and IS500)	Y	Y
Isola IS640	N	Y
BC2000	Y	Y
Rogers 4000 Series	Y	Y
Rogers 3000, 5000, 6000, TMM Series	N	Y
Arlon	N	Y
Nelco 4000, 5000, 7000, 8000, 9000 Series	N	Y
Thermagon	Y	Y
Gore Speedboard C, Speedboard N	N	Y
Bromine Free	N	Y
Taconics	N	Y

Surface Finishes		
HASL- RoHS compliant & Tin Lead	Y	Y
ENIG	Y	Y
Electrolytic Ni/Au	Y	Y
Immersion Sn	Y	Y
Immersion Ag	Y	Y
Selective Finishes	Y	Y
Wire Bondable Soft Electrolytic AU	Y	Y
OSP	Y	Y

Other	Standard	Advanced
Selective Bonding	Y	Y
Optical Drill	Y	Y
Impedance (Single Ended & Differential)	±10%	±5%
Buried Capacitance (Planar/Discrete)	Y	Y
Conductive / Non-Conductive Hole Fill	Y	Y
Metal Core (Al, Cu)	N	Y

Certifications		
UL certified	Y	Y
IPC J-STD-001	Y	Y
ROHS Compliant (Lead Free)	Y	Y
ISO 9001: 2008 Certified	Y	Y
ITAR Registered: Registrant Code M20447	N	Y
JCP Certified	N	Y
AS9100 Certified	Y	Y

Specifications as of May 17, 2010

Specifications are subject to change without notice.